



MJ N-Channel Enhancement Mode Power MOSFET

Description

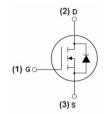
The MJ01H29TC uses advanced trench technology and design to provide excellent $R_{\text{DS}(\text{ON})}$ with low gate charge. It can be used in a wide variety of applications.

General Features

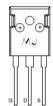
- ♦ V_{DS}=100V,I_D=290A R_{DS}(ON)<3.2mΩ @ V_{GS}=10V (Typ2.7mΩ)
- ◆ Good stability and uniformity with high E_{AS}
- ♦ High density cell design for ultra low Rdson
- ◆ Fully characterized avalanche voltage and current
- ◆ Excellent package for good heat dissipation

Application

- DC motor drive
- ♦ High efficiency synchronous rectification in SMPS
- ◆ Uninterruptible power supply
- ◆ High speed power switching
- ◆ Hard switched and high frequency circuits







Marking and pin assignment



TO-247 top view

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ01H29TC	MJ01H29TC	TO-247	-	-	-

Absolute Maximum Ratings (Tc =25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	100	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	290	А
Drain Current-Continuous(Tc =100°C)	ID(100°C)	200	А
Pulsed Drain Current	Ідм	1120	А
Maximum Power Dissipation	Po	460	W
Single pulse avalanche energy (Note 3)	Eas	3500	mJ
Derating factor		3.07	W/°C
Peak Diode Recovery dv/dt (Note 4)	dv/dt	10	V/ns
Operating Junction and Storage Temperature Range	Тл,Тѕтс	-55 To 175	°C

Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 1)	Reja	0.33	°C/W
	1 100/1	0.00	





Electrical Characteristics (TA =25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	'					
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =250μA	100	110	-	V
Zero Gate Voltage Drain Current	loss	V _{DS} =100V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	lgss	V _{DS} =±20V,V _{DS} =0V	-	-	±200	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =250µA	2	3	4	V
Drain-Source On-State Resistance	Rds(on)	V _{GS} =10V, I _D =40A	-	2.7	3.2	mΩ
Forward Transconductance	grs	V _{DS} =25V,I _D =40A	310	-	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	Clss		-	16000	-	PF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V, F=1.0MHz	-	1352	-	PF
Reverse Transfer Capacitance	Crss	-	-	1061	-	PF
Switching Characteristics (Note 4)	-					
Turn-on Delay Time	t _{d(on)}		-	44.6	-	nS
Turn-on Rise Time	tr	VDD=50V,ID=40A	-	29.4	-	nS
Turn-Off Delay Time	td(off)	V _{GS} =10V,R _{GEN} =1.2 Ω ^(Note2)	-	139.8	-	nS
Turn-Off Fall Time	tr		-	36.4	100	nS
Total Gate Charge	Qg		-	469	-	nC
Gate-Source Charge	Qgs	V _{DS} =30V,I _D =30A, V _{GS} =10V ^(Note2)	-	99	-	nC
Gate-Drain Charge	Qgd	-	-	148	-	nC
Drain-Source Diode Characteristics						<u>I</u>
Diode Forward Voltage	VsD	V _{GS} =0V,I _S =40A	-	-	1.2	V
Reverse Recovery Time	trr	TJ=25°C, IF=40A	-	87.9	-	nS
Reverse Recovery Charge	Qrr	di/dt=100A/µs ^(Note 2)	-	129	-	nC
Forward Turn-On Time	ton	Intrinsic turn-on time is negligible(turn-on is dominated by LS			W S+ L	

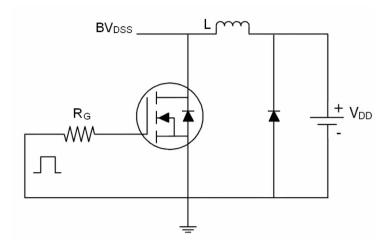
Notes:

- ① Surface Mounted on FR4 Board, t≤10sec.
- ② Pulse Test: Pulse Width≤400µs, Duty Cycle≤2%.
- 4 Isp \leq 125A, di/dt \leq 260A/ μ s, Vpp \leq V(BR)pss, T $_{J}\leq$ 175°C

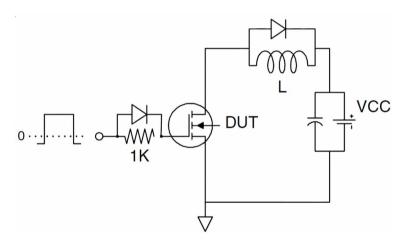




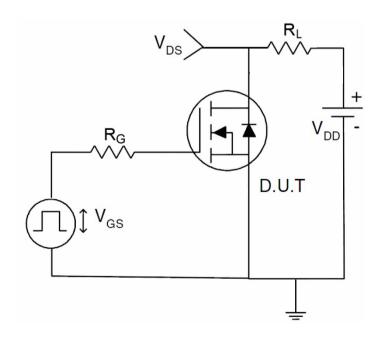
Test circuit



Eas test Circuit



Gate charge test Circuit



Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

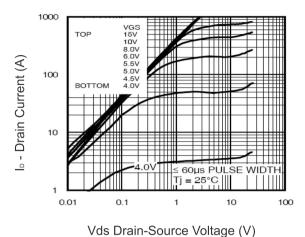
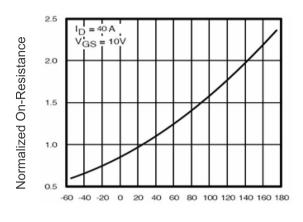


Figure 1 Output Characteristics



TJ -Junction Temperature(°C)
Figure 4 Rdson-Junction Temperature

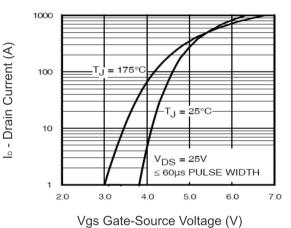
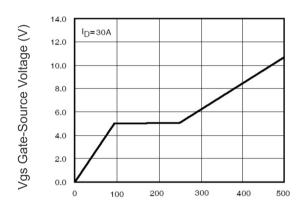


Figure 2 Transfer Characteristics



Qg Gate Charge (nC)
Figure 5 Gate Charge

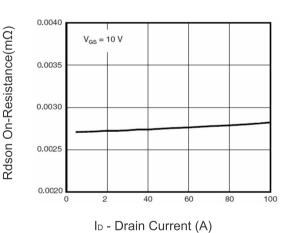


Figure 3 Rdson- Drain Current

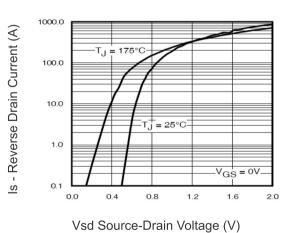


Figure 6 Source- Drain Diode Forward



le - Drain Current (A)

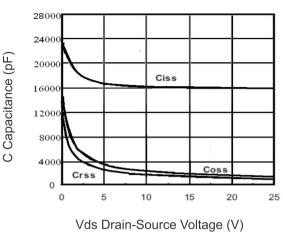
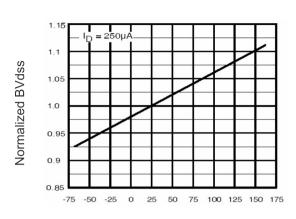


Figure 7 Capacitance vs Vds



T_J -Junction Temperature(°C) Figure 9 BVDSS vs Junction Temperature

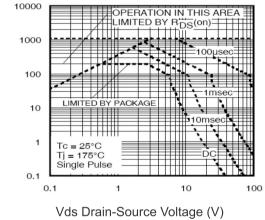
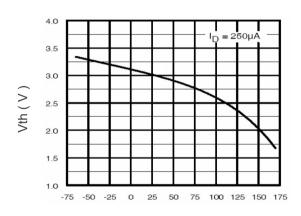


Figure 8 Safe Operation Area



T_J -Junction Temperature(°C) Figure 10 V_{GS(th)} vs Junction Temperature

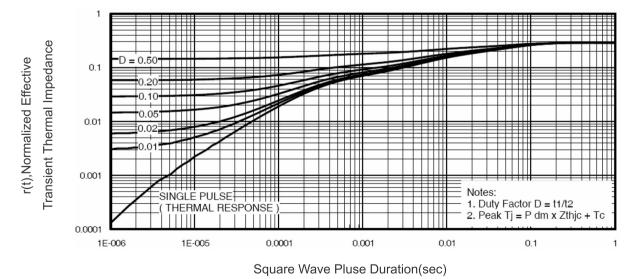
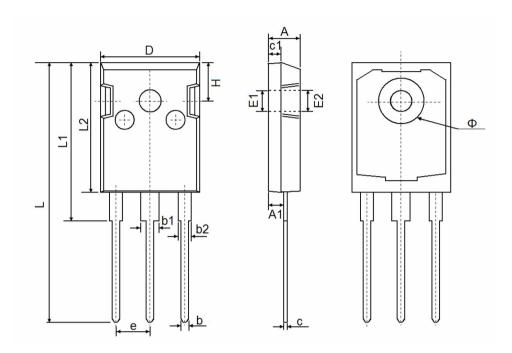


Figure 11 Normalized Maximum Transient Thermal Impedance





TO-247 Package Information



Comple of	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.850	5.150	0.191	0.200	
A1	2.200	2.600	0.087	0.102	
b	1.000	1.400	0.039	0.055	
b1	2.800	3.200	0.110	0.126	
b2	1.800	2.200	0.071	0.087	
С	0.500	0.700	0.020	0.028	
c1	1.900	2.100	0.075	0.083	
D	15.450	15.750	0.608	0.620	
E1	3.500) REF	0.138 REF		
E2	3.600	3.600 REF		REF	
L	40.900	41.300	1.610	1.626	
L1	24.800	25.100	0.976	0.988	
L2	20.300	20.600	0.799	0.811	
Ф	7.100	7.300	0.280	0.287	
е	5.450 TYP		0.215 TYP		
Н	5.980) REF	0.235 REF		





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